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**MIRTEC to Exhibit Its Award-Winning
3D AOI and 3D SPI Systems at SMTAI 2016**

August 2016 – MIRTEC, “The Global Leader in Inspection Technology,” will premier its award-winning 3D AOI and 3D SPI systems in Booth #707 at the 2016 SMTA International Exhibition. The exhibition will take place September 27-28, 2016 at the Donald Stephens Convention Center located in Rosemont, IL.

“MIRTEC will feature our award-winning MV-6 OMNI 3D AOI and MS-11e 3D SPI systems at this year’s event,” stated Brian D’Amico, President of MIRTEC’s North American Sales and Service Division. “Market demand for these two revolutionary products has led to three straight quarters of unprecedented growth of our organization. We are very excited about exhibiting at this year’s SMTAI event.”



The award-winning **MV-6 OMNI 3D AOI Machine** is configured with MIRTEC’s exclusive OMNI-VISION® 3D Inspection Technology which combines our 15 Mega Pixel CoaXPress Camera Technology with MIRTEC’s revolutionary Digital Multi-Frequency Quad Moiré 3D system in a newly designed cost-effective platform. MIRTEC’s 15 Mega Pixel CoaXPress Vision System is a proprietary camera system designed and manufactured by MIRTEC for use with its complete product range of 3D inspection systems.

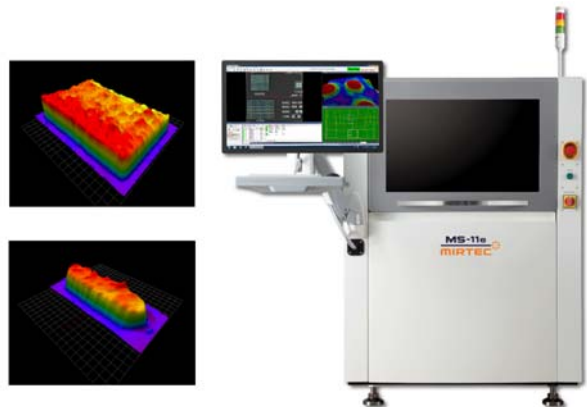
MIRTEC’s Digital Multi-Frequency Quad Moiré Technology, provides true 3D inspection using a total of four (4) Programmable Digital Moiré Projectors to yield precise height measurement data used to detect lifted component and lifted lead defects as well as solder volume post reflow. Fully configured, the new MIRTEC MV-

6 OMNI machines feature four (4) 10 Mega Pixel Side-View Cameras in addition to the 15 Mega Pixel Top-Down Camera. There is little doubt that this new technology has set the standard by which all other inspection equipment is measured. MIRTEC will have two (2) MV-6 OMNI’s on display one configured with a 10um lens for High-Performance applications and the other with a 15um lens for High-Speed applications.

The **MS-11e 3D SPI Machine** is configured with MIRTEC’s exclusive 15 Mega Pixel CoaXPress Vision System, providing enhanced image quality, superior accuracy and incredibly fast inspection rates.

The machine uses Dual Projection “Shadow Free” 3D Moiré Technology combined with a Precision Telecentric Compound Lens and Precision Laser PCB Warpage Compensation to accurately characterize each solder deposition post-screen print.

The MS-11e precisely measures solder volume, area, shape deformity and X/Y position, and inspects for bridging between adjacent solder depositions. Furthermore, the MS-11e provides real-time closed-loop feedback to the screen printing system to effectively eliminate defects before they occur!





MIRTEC's total quality management system software, **INTELLISYS**[®] also will be on display at SMTAI 2016. This software suite promotes continuous process improvement by allowing manufacturers to track and eliminate defects on inspected assemblies.

"MIRTEC has earned a solid reputation in the industry by providing unprecedented performance, quality and cost-effectiveness to the inspection environment," continued D'Amico, "We look forward to welcoming visitors to our booth #707 during the two-day event."

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MIRTEC is a leading global supplier of automated inspection systems to the electronics manufacturing industry. For further information, please visit www.mirtec.com.